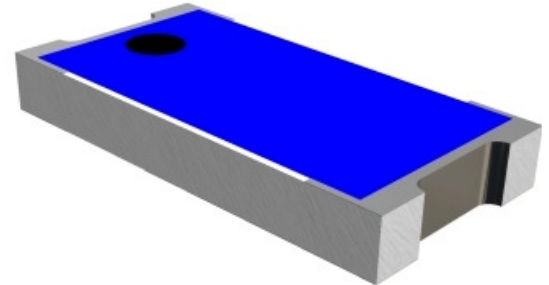


FEATURES

- Low Profile Surface Mount
- High Power
- Low VSWR
- Ideal For Automated Assembly

APPLICATIONS

- Mobile Networks
- Broadcast
- High Power Amplifiers
- Instrumentation
- Isolators
- Military
- Satellite Communications



GENERAL DESCRIPTION

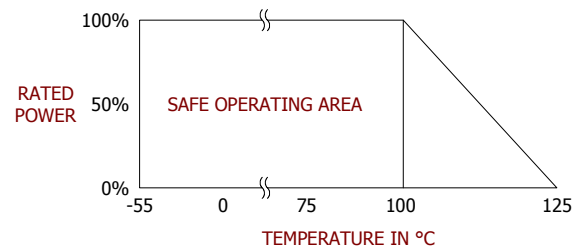
EMC Technology's surface mount terminations are designed for direct installation on printed circuit boards and manufactured using thick film technology. Edge metallization on two sides forms the solder fillets for stronger attachment, easier inspection, and increased heat removal area. The devices are available in Alumina, Aluminum Nitride or Beryllium Oxide.

SPECIFICATIONS

1.0 ELECTRICAL

- Nominal Impedance: 50 Ω
- Frequency Range: DC – 6.0 GHz
- VSWR: 1.25:1 Max @ DC - 3.0 GHz
1.60:1 Max @ 3.0 - 6.0 GHz
- Temperature Coefficient: ± 200 PPM/ $^{\circ}$ C Max
- Power Rating: 8 Watts (Derating Chart)
- Operating Temperature: -55 $^{\circ}$ C To +125 $^{\circ}$ C
- DC Resistance: 50 $\Omega \pm 5\%$

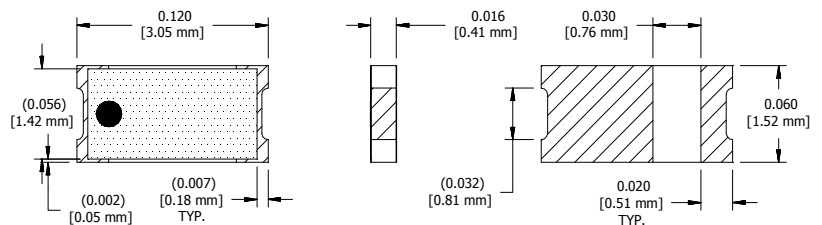
POWER RATING AND DERATING



2.0 MECHANICAL

- Substrate: Alumina
- Resistive Film: Thick Film
- Metallization: Thick Film, Silver Plated

MECHANICAL OUTLINE



3.0 UNIT MARKING

Input Dot

4.0 PACKAGING

- Standard: Tape and Reel
- Optional: Available Upon Request

5.0 PART

- Part Identifier: SMT1206AF

Unless otherwise specified: TOLERANCE: $\pm .010$

* Note: Specifications are subject to change without notice.

**NOTE: Power handling may vary depending on mounting and heat sinking method.